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Kobayashi et al.

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(54) **INFRARED LAMP HEATER TRANSMISSION WINDOW FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/184; D26/138**

(58) **Field of Classification Search**
USPC D13/184; D26/1, 24, 74, 72, 36, 59, 118, D26/133, 134
CPC H01R 5/00; H01R 13/46; H01R 13/514; H01R 31/02; F21V 5/00; H01J 19/54; H01J 5/48; H01J 1/02; H01J 5/16; H01J 5/00; H01J 5/50; H01L 33/642; H01L 33/643; H01L 33/644

See application file for complete search history.

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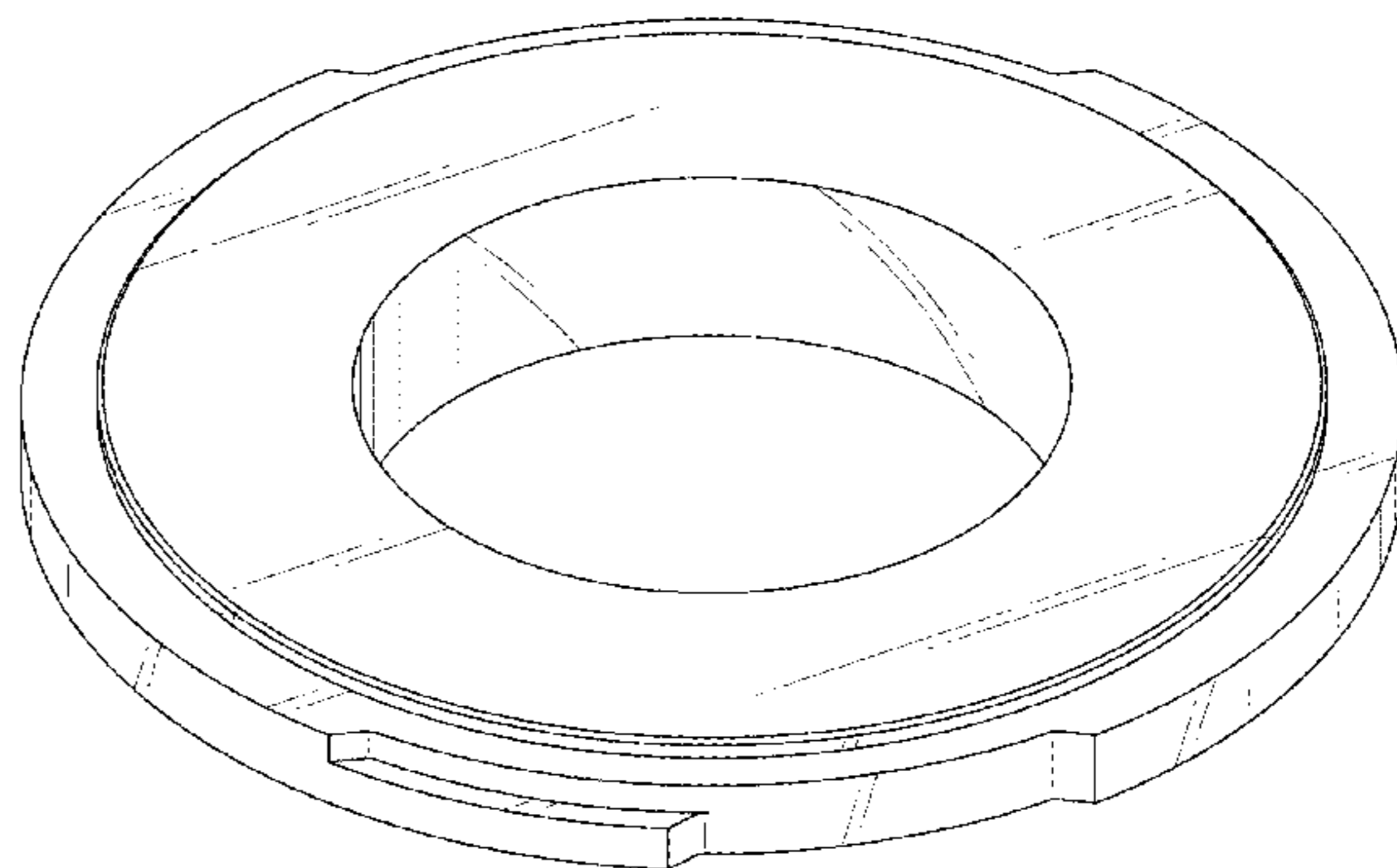
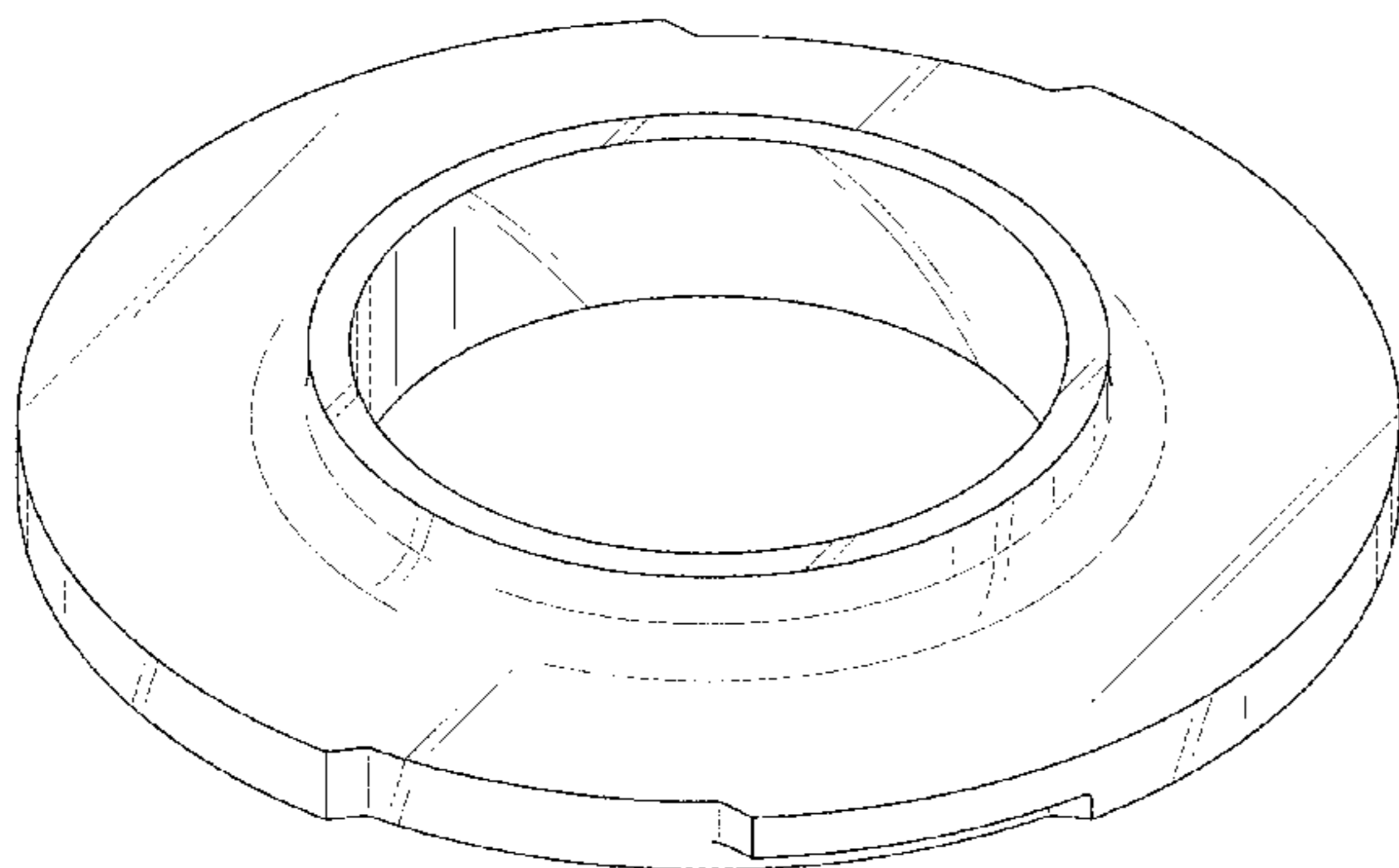
(57) **CLAIM**

The ornamental design for an infrared lamp heater transmission window for semiconductor manufacturing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of an infrared lamp heater transmission window for semiconductor manufacturing apparatus according to the design;
FIG. 2 is a rear, bottom and left side perspective view thereof;
FIG. 3 is a front elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof;
FIG. 8 is a rear elevational view thereof;
FIG. 9 is an end view taken along line 9-9 of FIG. 3; and,
FIG. 10 is an end view taken along line 10-10 of FIG. 8.

1 Claim, 5 Drawing Sheets



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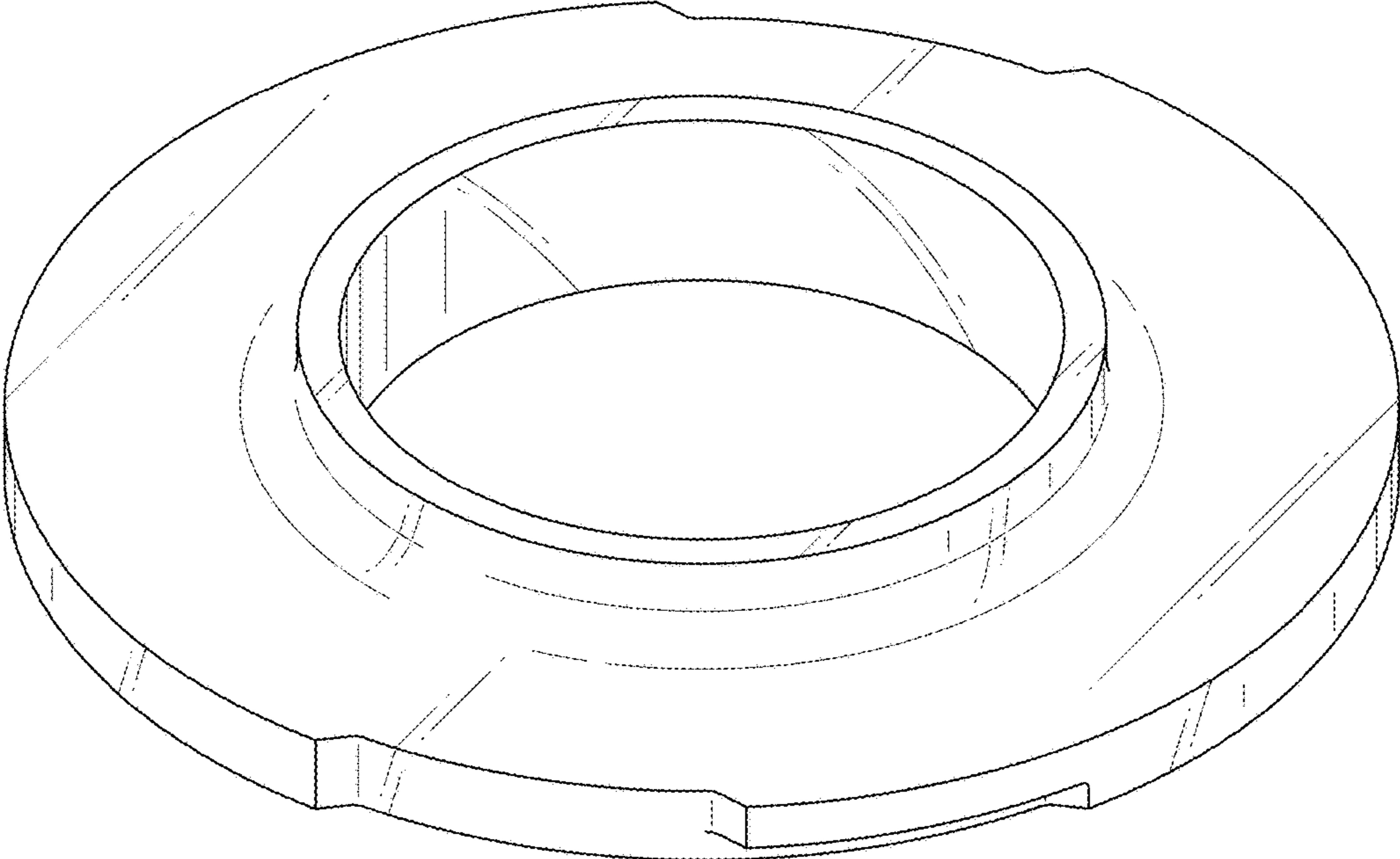


FIG. 1

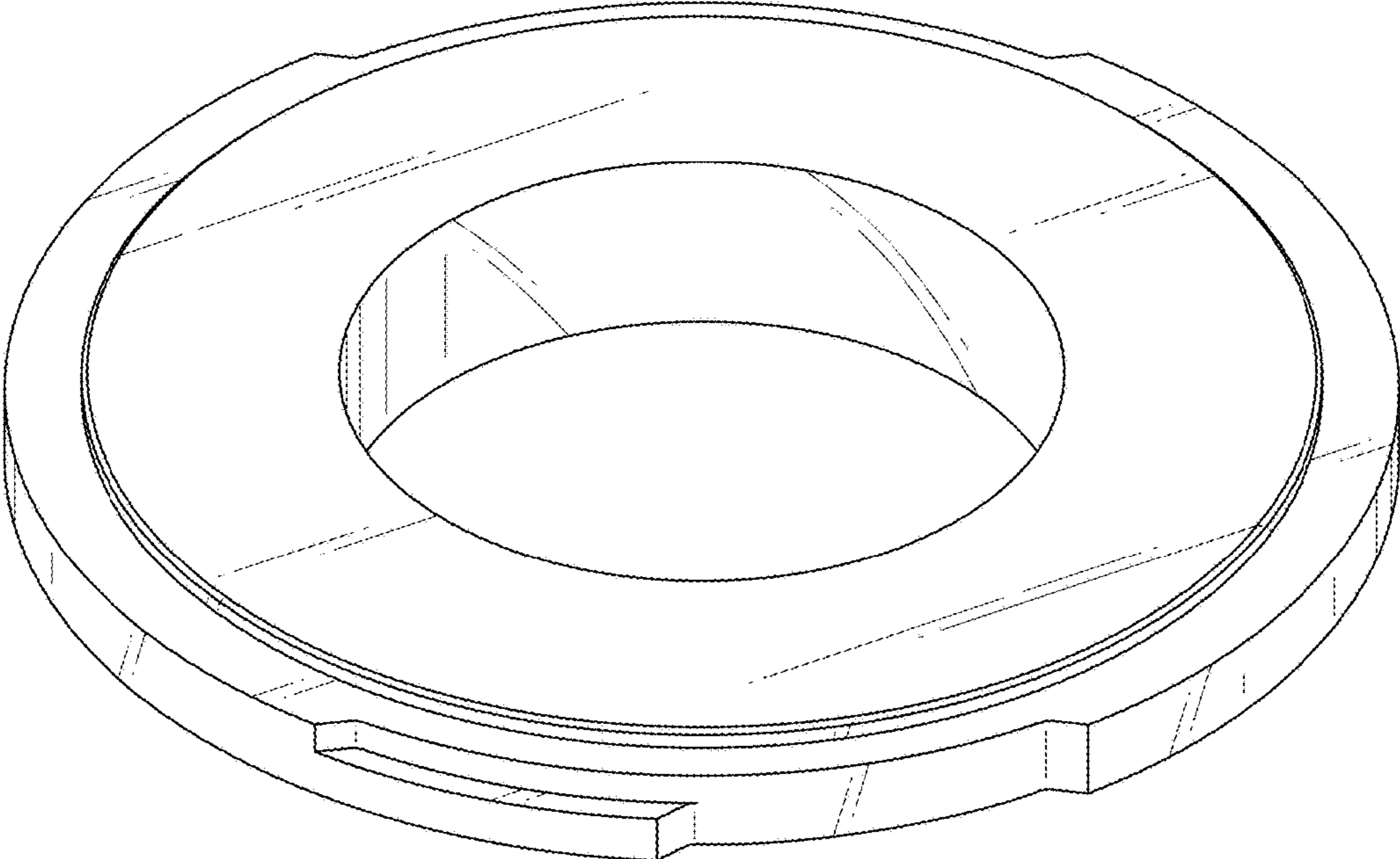


FIG. 2

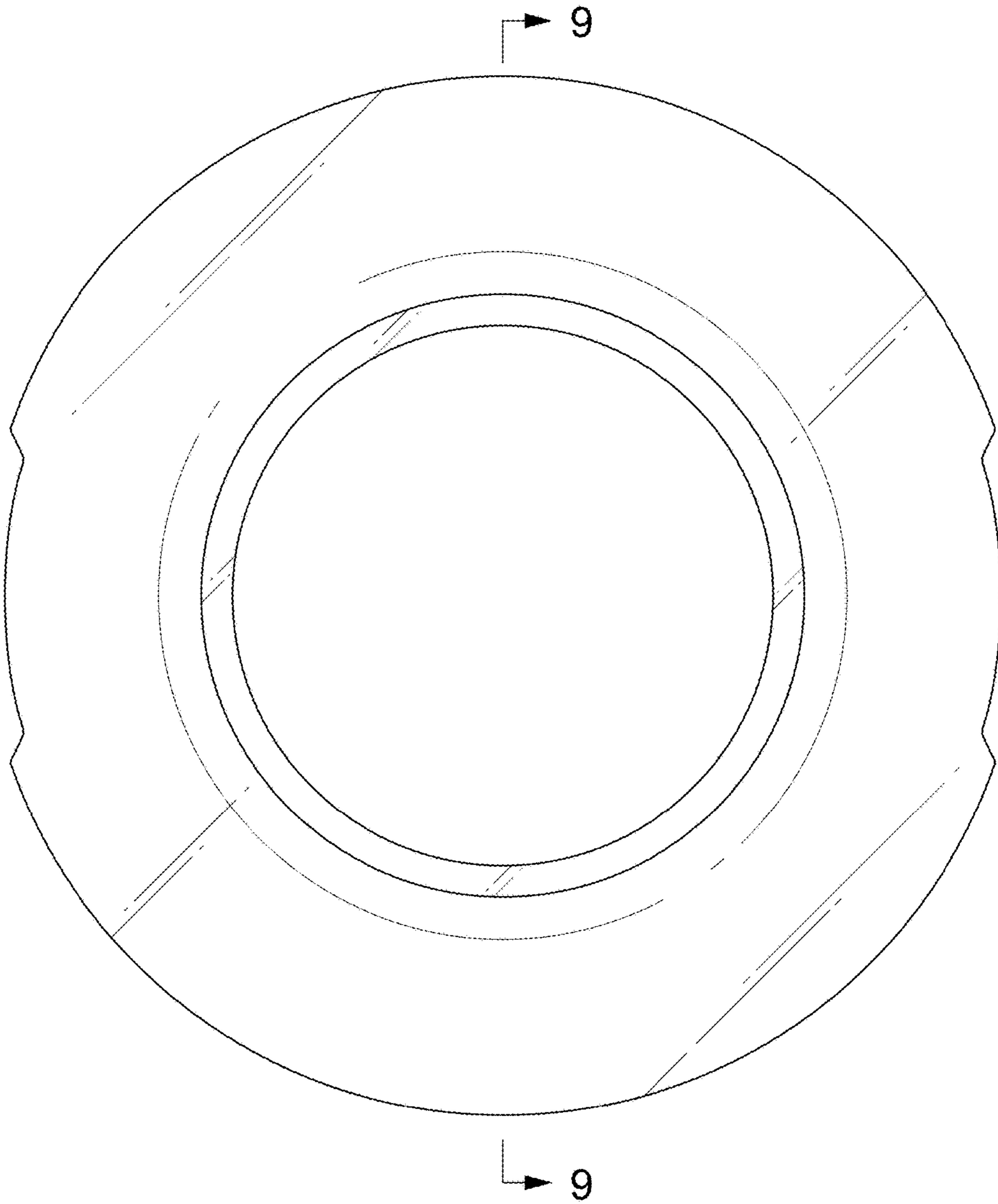


FIG. 3

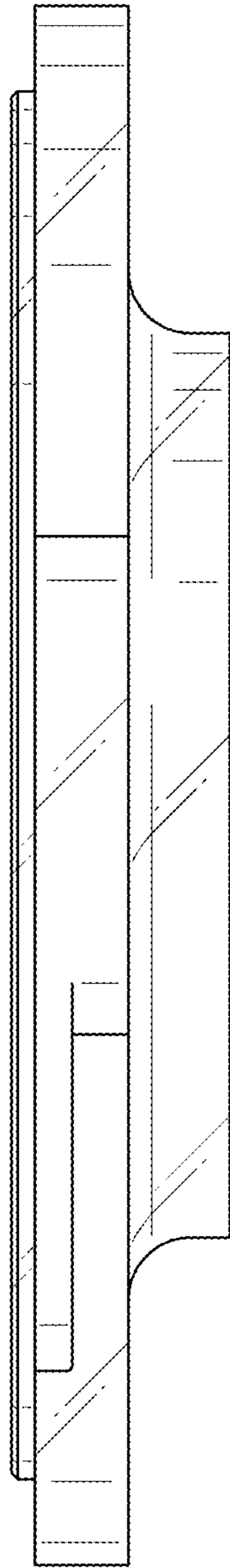


FIG. 4

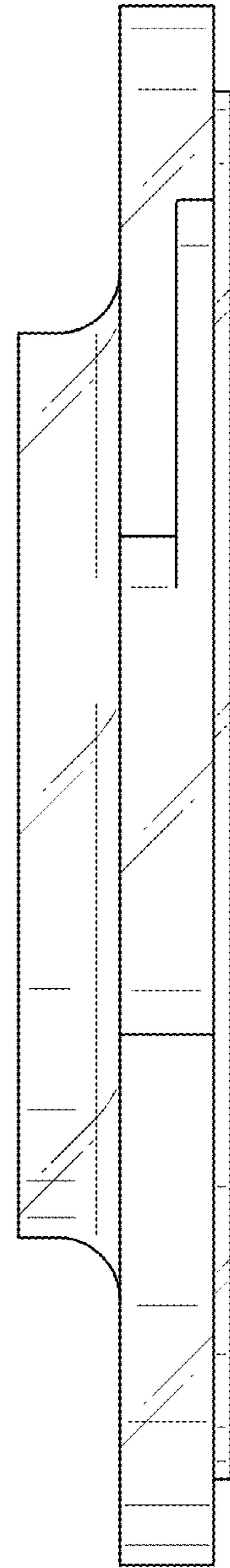


FIG. 5

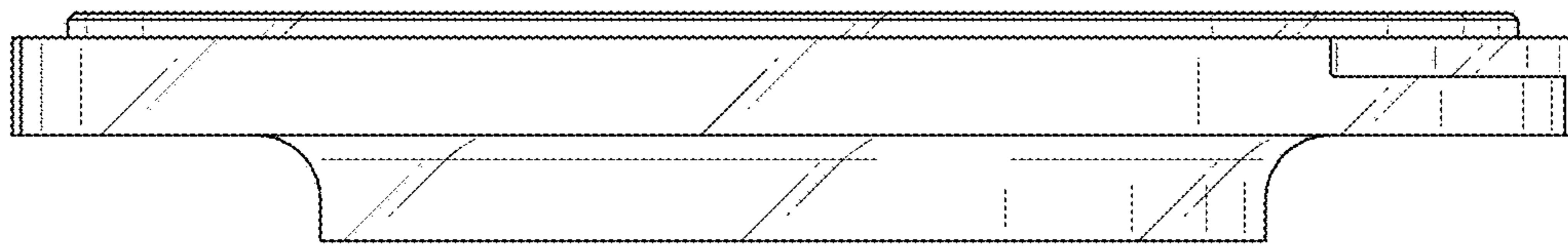


FIG. 6

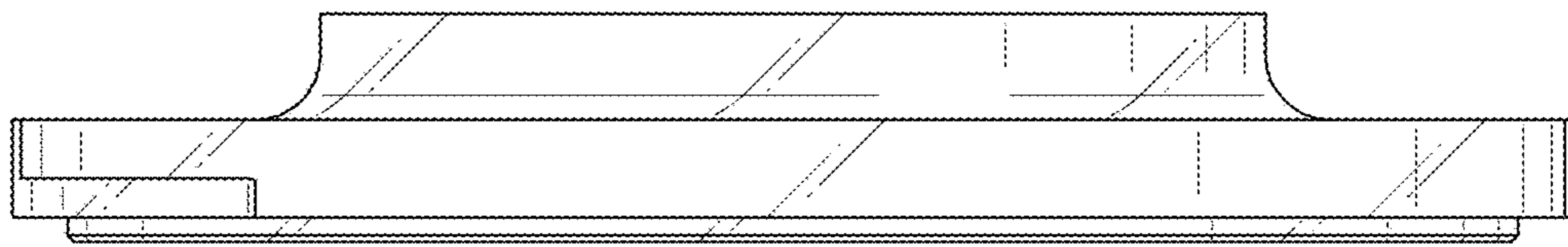


FIG. 7

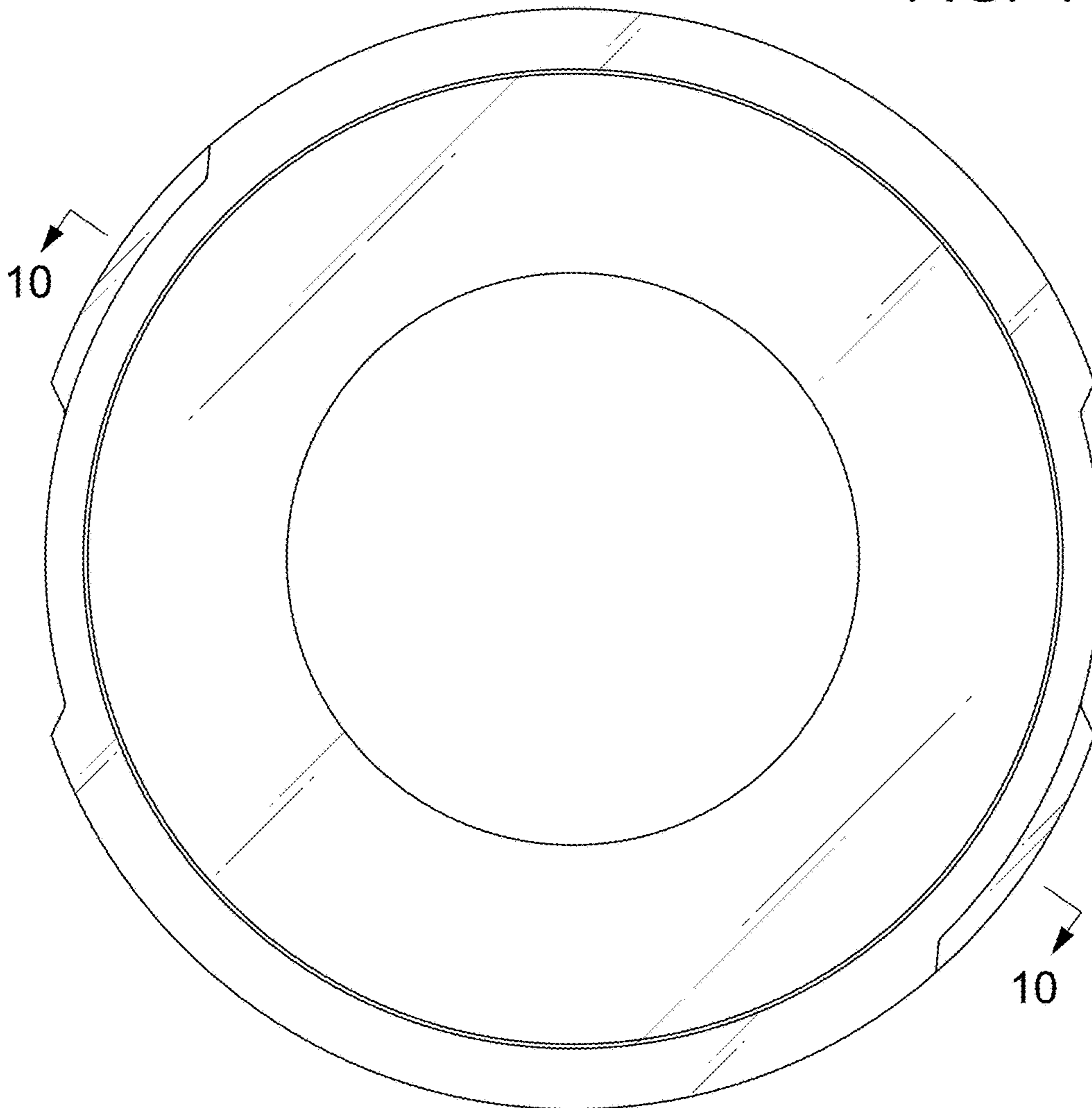


FIG. 8

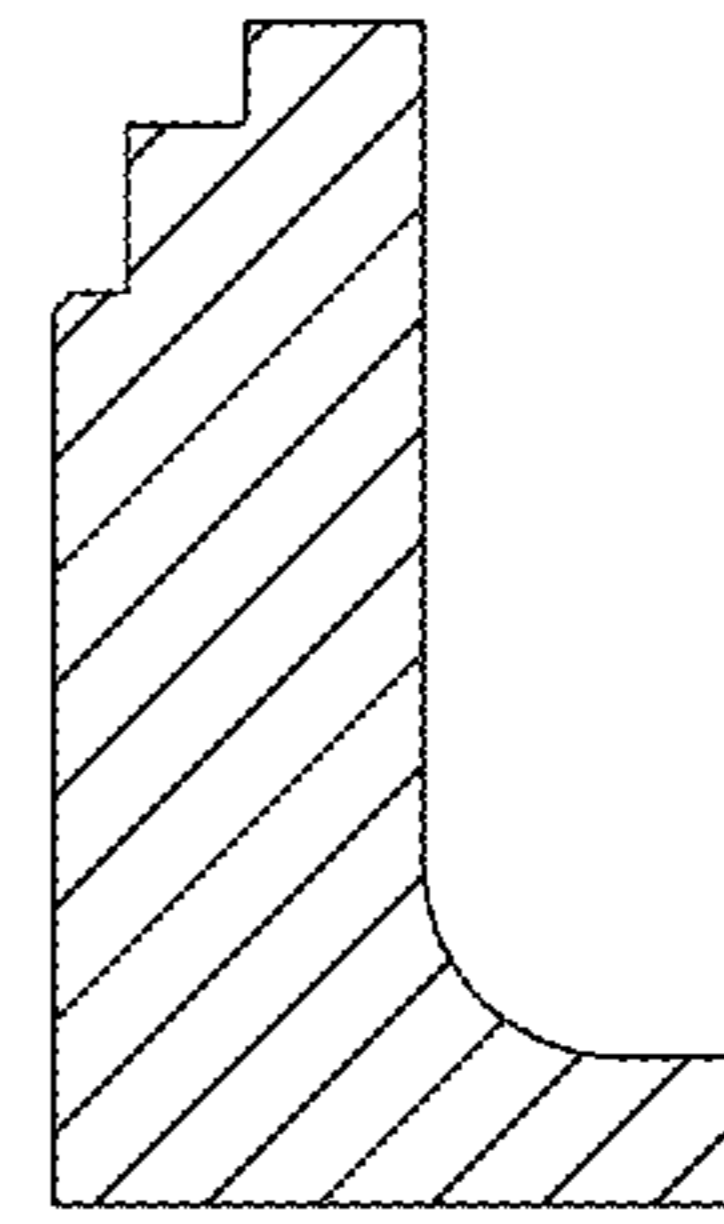
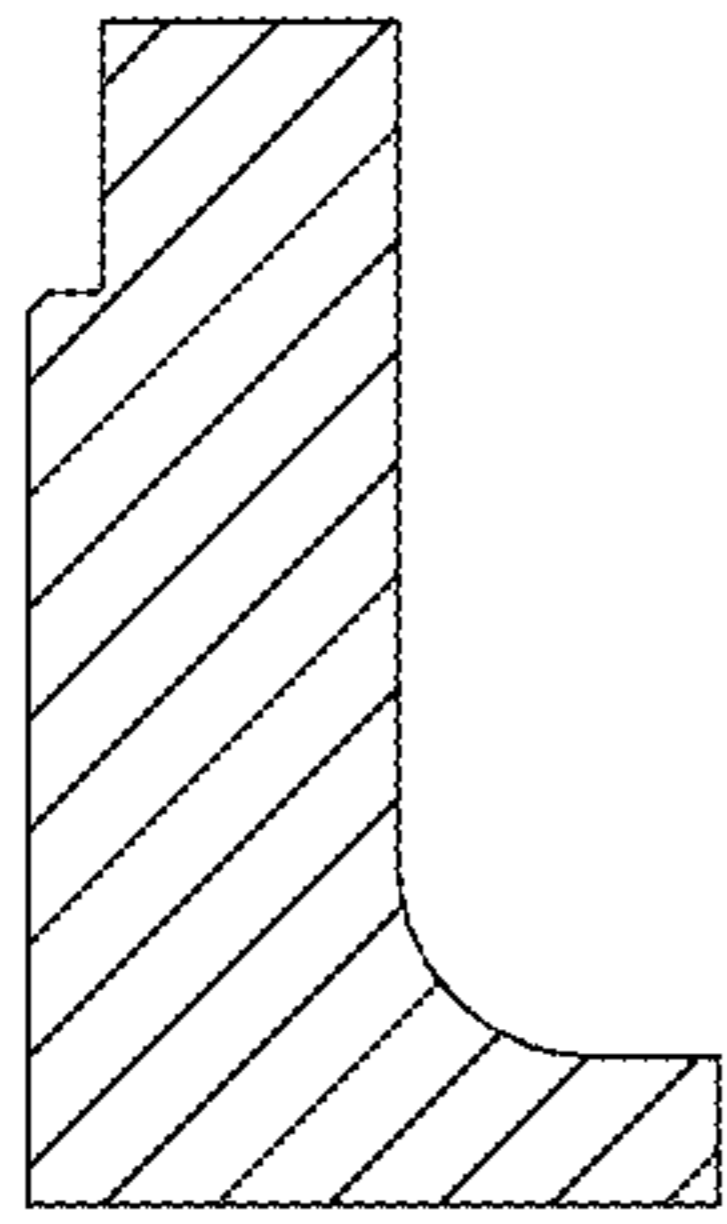


FIG. 9

FIG. 10